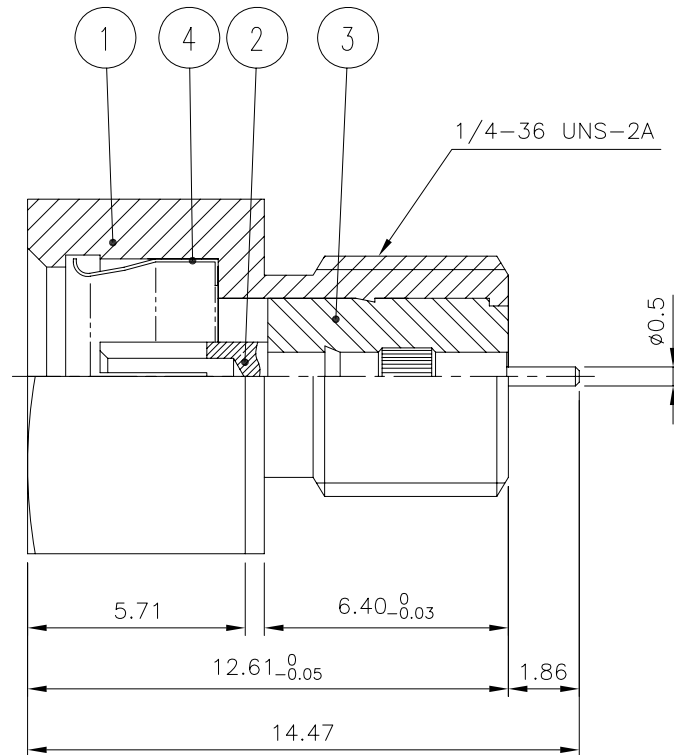
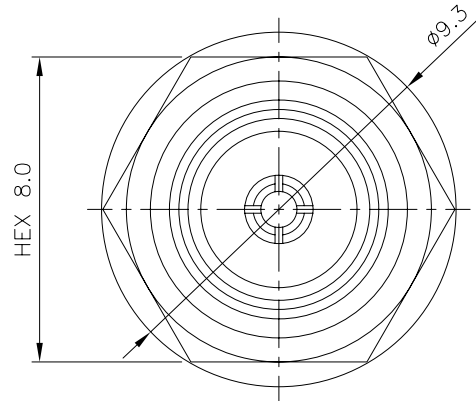


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	I.C.KIM	2013.12.05.



★ 주 기

1. 삽입력 Spec (상대물 Ø0.92)

- 삽입력 Spec : 0.2~0.3Kgf

- 이탈력 Spec : 0~0.1Kgf

4	JACK	1	BeCu	Gold Plate	DPS00002-5/1
3	INSULATOR	1	TEFLON		DIN02292-N/1
2	CONTACT	1	BeCu	Gold Plate (1.27μm)	DCT03000-5/1
1	BODY	1	SUS303	부동태 처리	DBD03506-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2013. 12. 05.		 KJ COMTECH CO.,LTD. RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY	E.H.KIM	TITLE BMA50 SOLDER END JB(F/F)
		DRAWN BY	I.C.KIM	
FINISH		SCALE	5/1	A4 DWG NO. CN02999-7/2 REVISION I R SHEET 1 of 1
		UNIT	mm	